

GODDARD SPACE FLIGHT CENTER

Test Lab Report Summary

<i>Report Number:</i>	Q10173DPA	<i>Project:</i>	SWIFT
<i>Part Type:</i>	Microcircuit	<i>System:</i>	BAT
<i>Part Number:</i>	OP420GS	<i>Initiated Date:</i>	05/01/2001
<i>Date Code:</i>	9940	<i>Report Date:</i>	08/14/2001
<i>Manufacturer:</i>	Analog Devices	<i>Investigator:</i>	C. Greenwell (562)
<i>Generic Number:</i>	OP420	<i>Requester:</i>	B. Meinhold (562)
<i>Purchase Spec:</i>	Commercial	<i>Approval / Date:</i>	

Step 1: INCOMING INSPECTION

<u>Test</u>	<u>Quantity</u>	<u>Passed</u>	<u>Failed</u>
External Visual	N/A	N/A	N/A
PIND Condition A	N/A	N/A	N/A

Step 2: DESTRUCTIVE PHYSICAL ANALYSIS

Destructive Physical Analysis (DPA) was conducted per GSFC document "Plastic Encapsulated Microcircuit (PEM) Guidelines for Screening and Qualification for Space Applications", except that cross-section was done without dye penetrant and glassivation integrity testing was not performed.

No rejectable defects or anomalies were observed during this analysis.

GODDARD SPACE FLIGHT CENTER

Part Type: Microcircuit Part No: OP420GS
 Manufacturer: Analog Devices Date Code: 9940

Summary of Analysis:

	<i>Serial Number</i>	<u>18</u>	<u>21</u>	<u>24</u>	<u>27</u>	<u>30</u>
<i>External Examination</i>						
1. Markings - legibility and correctness _____		A	A	A	A	A
2. Integrity of package seals _____		N/A	N/A	N/A	N/A	N/A
3. Condition of external leads and plating _____		A	A	A	A	A
4. Overall package condition _____		A	A	A	A	A
<i>Radiographic Examination</i>						
5. Die bonding material and die alignment _____		A	A	A	A	A
6. Package seal integrity _____		N/A	N/A	N/A	N/A	N/A
7. Presence of foreign material _____		A	A	A	A	A
8. Lead dress (if revealed) _____		A	A	A	A	A
<i>Acoustic Microscopy Inspection</i>						
9. Condition of material interfaces (delaminations) _____		A	A	A	A	A
10. Condition of molding material (voids, cracks) _____		A	A	A	A	A
<i>Internal Examination (including cross-section)</i>						
11. Presence of foreign material _____		A	A	A	A	A
12. Mechanical condition of die _____		A	A	A	A	A
13. Wire bonds and lead dress _____		N/P	N/P	A	A	A
14. Die bonding material _____		N/P	N/P	A	A	A
15. Condition of die surface _____		N/P	N/P	A	A	A
16. Condition of metallization _____		N/P	N/P	A	A	A
17. SEM Examination _____		N/P	N/P	A	A	A
<i>Bond Strength</i>						
18. Strength _____		N/P	N/P	A	A	A
19. Metallization adherence _____		N/P	N/P	A	A	A
<i>Die Bond Strength</i>						
20. Strength _____		N/P	N/P	N/P	N/P	N/P

SN's 18 and 21 subjected to cross-sectional examination.

(* = Refer to comments, A = acceptable, U = unacceptable, N/A = not applicable, N/P = not performed)

Appended Photographs:

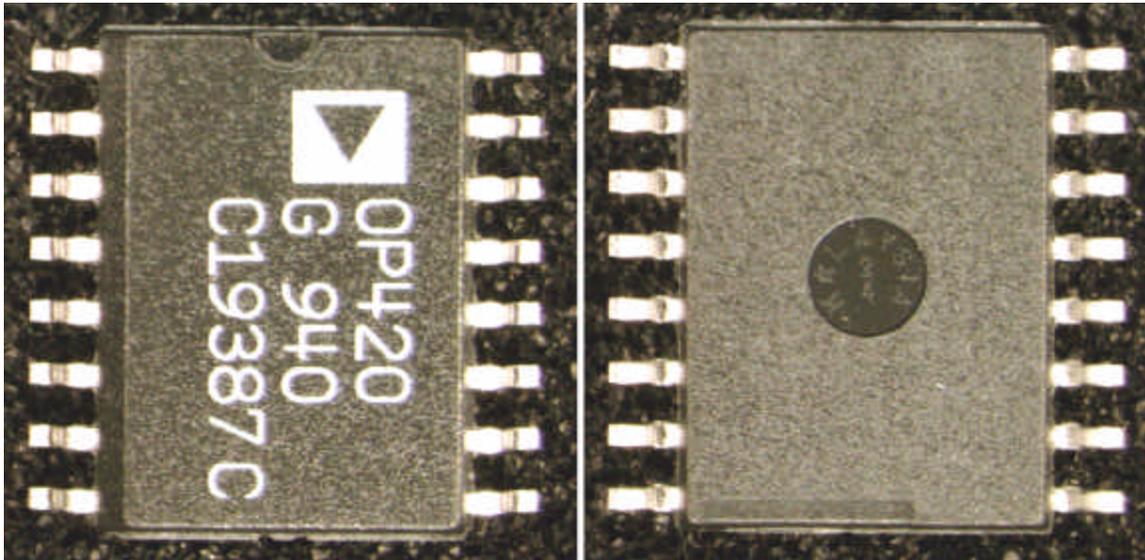


Figure 1. External top and bottom views of the OP420GS devices. Each device had a unique two character numeric code that was used for reference designations during this analysis. 6X

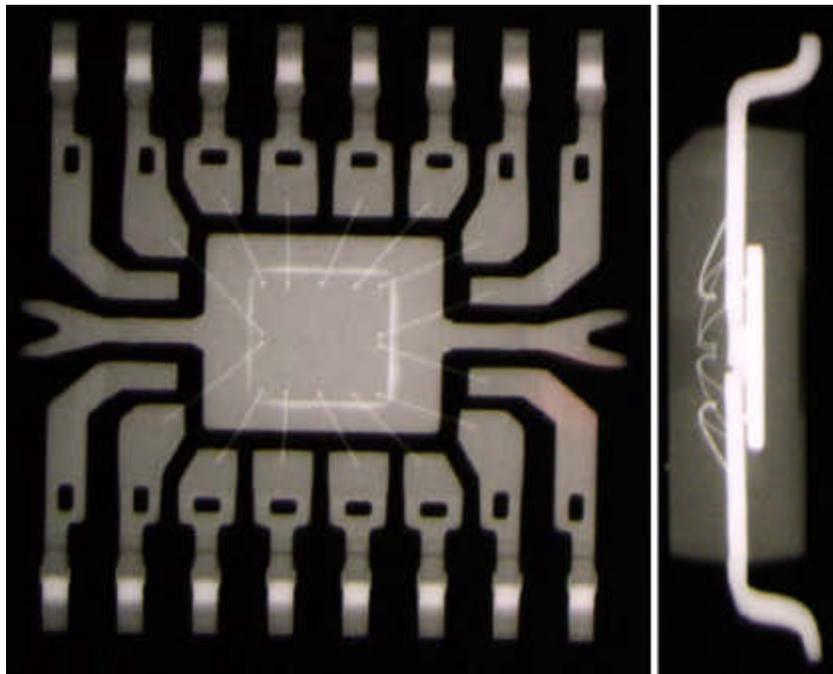


Figure 2. Top and side view radiographic images. 8X

Appended Photographs:

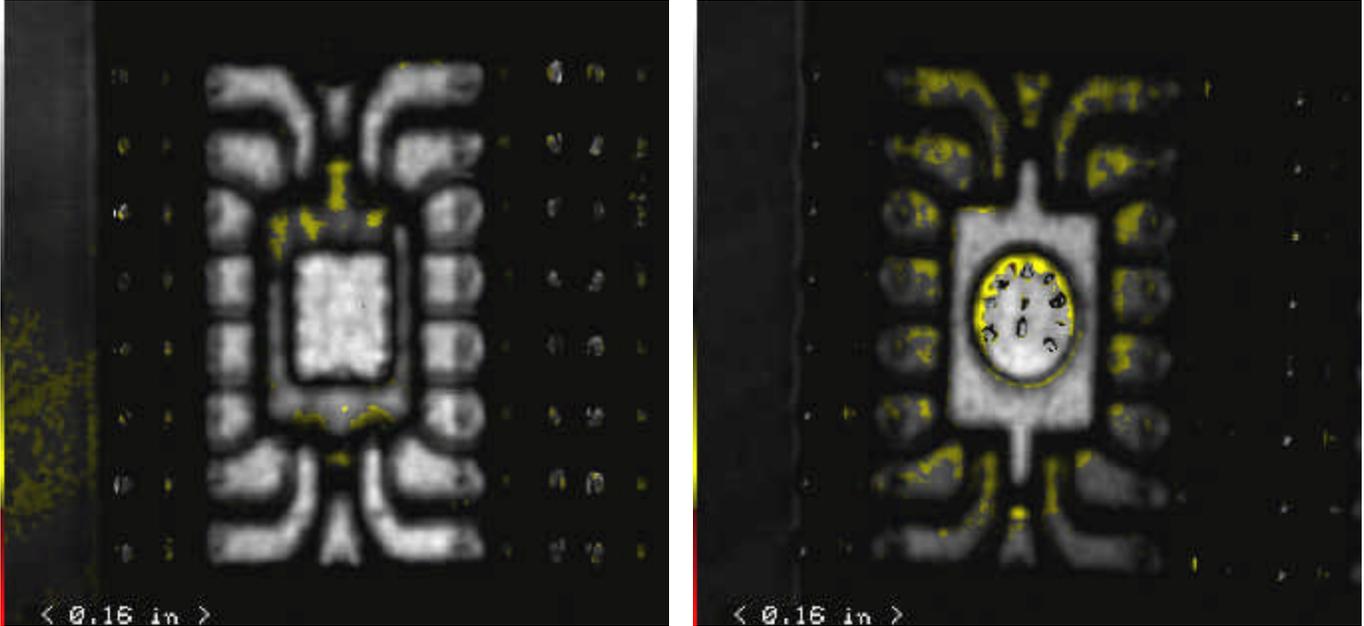


Figure 3. Top (left) and bottom C-SAM images of SN 18. Yellow areas are artifact of the tool settings.

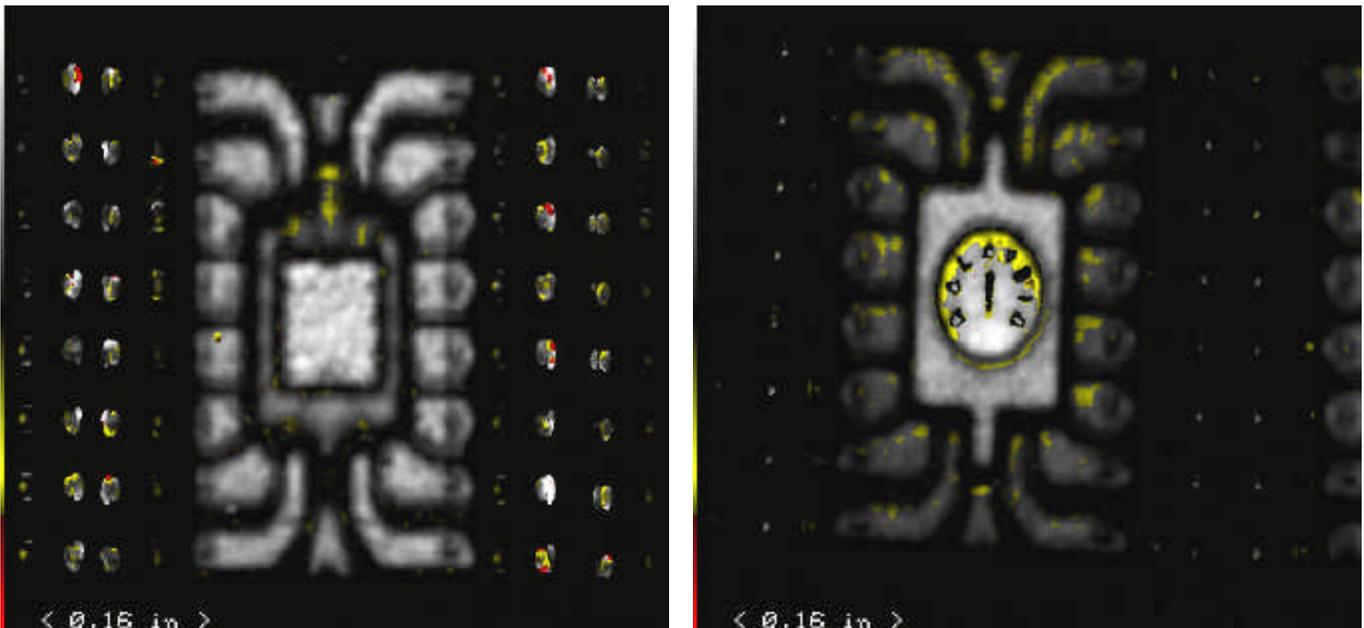


Figure 4. Top (left) and bottom C-SAM images of SN 21.

Appended Photographs:

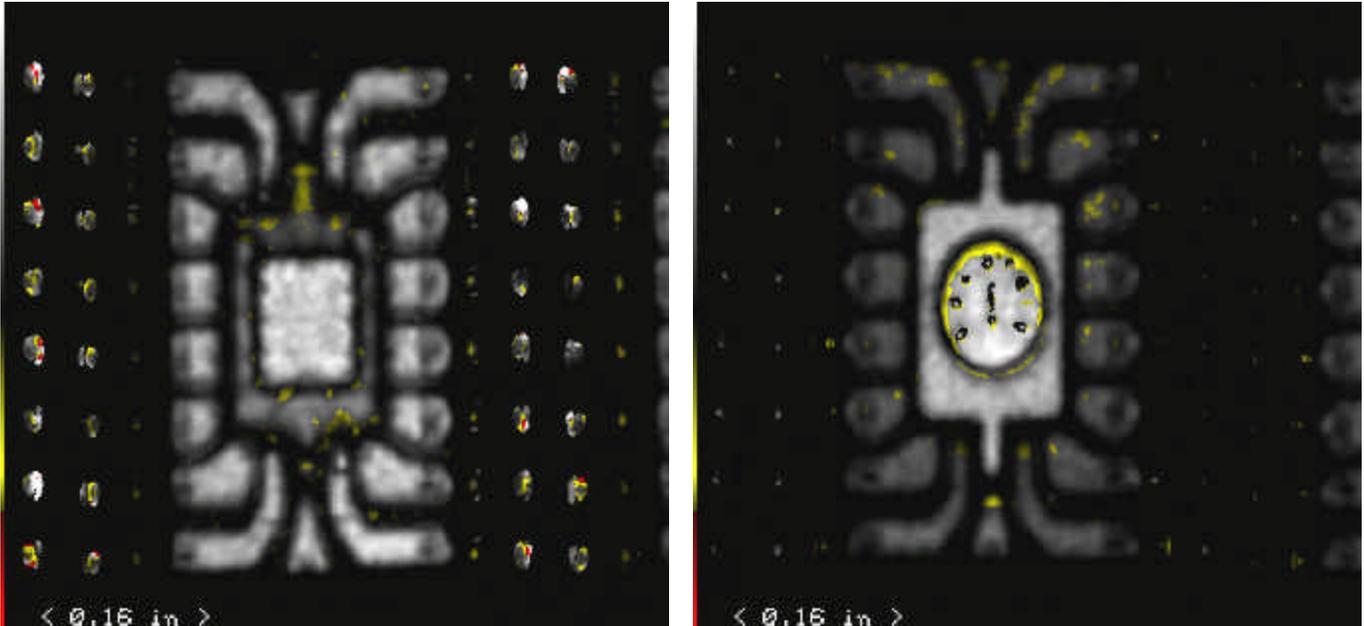


Figure 5. Top (left) and bottom C-SAM images of SN 24.

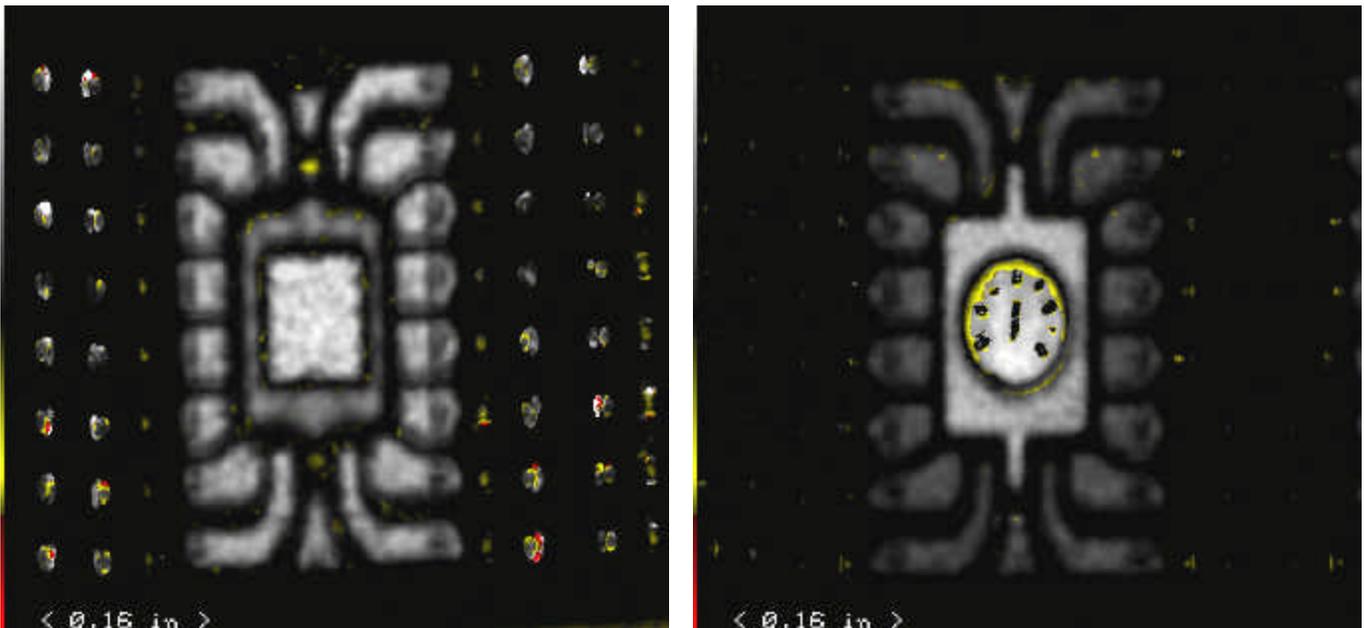


Figure 6. Top (left) and bottom C-SAM images of SN 27.

Appended Photographs:

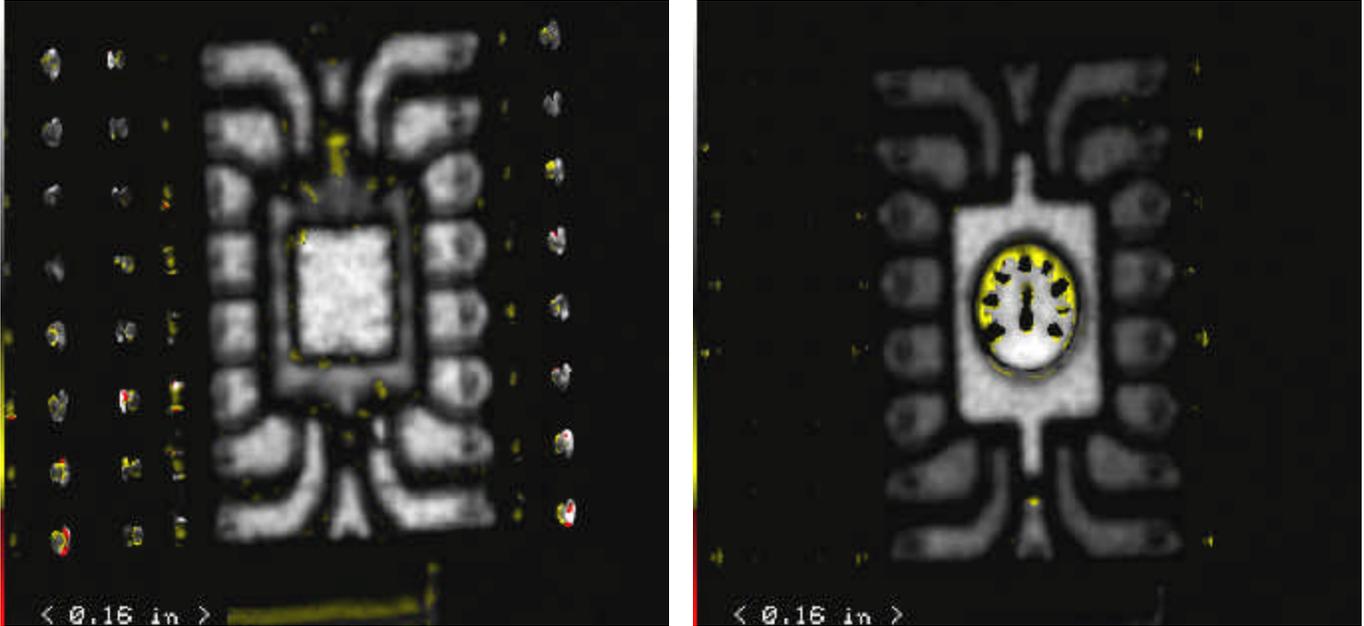


Figure 7. Top (left) and bottom C-SAM images of SN 30.

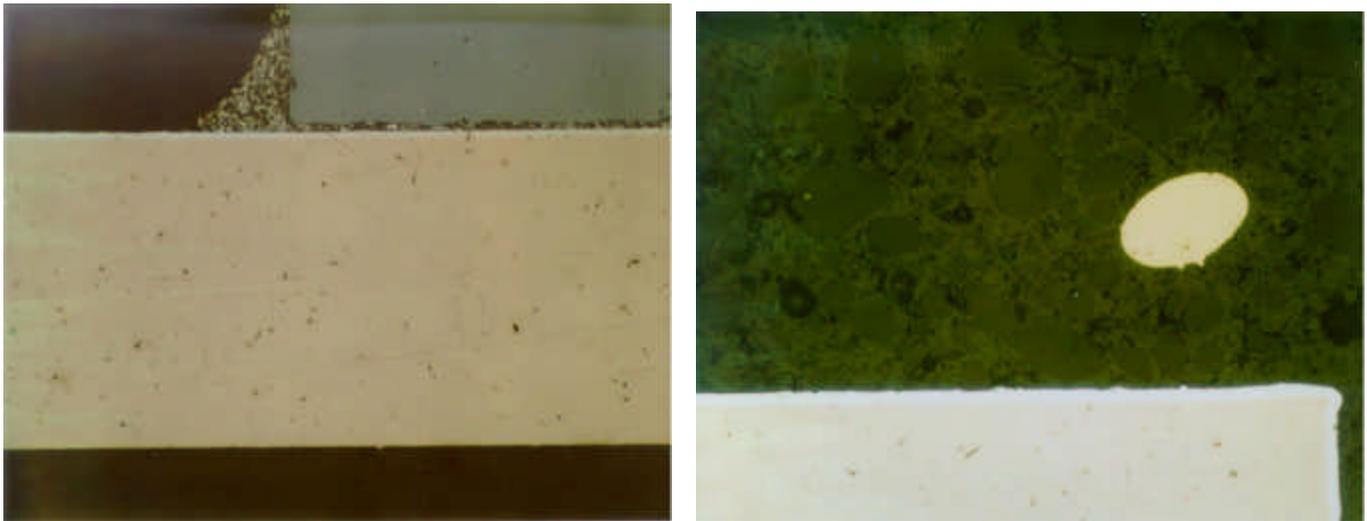


Figure 8. Cross-section images of SN 18. Left \approx 200X; right \approx 200X.

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Part Type: Microcircuit
Manufacturer: Analog Devices

Part No: OP420GS
Date Code: 9940

Appended Photographs:



Figure 9. Cross-section images of SN 21. Both images $\approx 200X$.

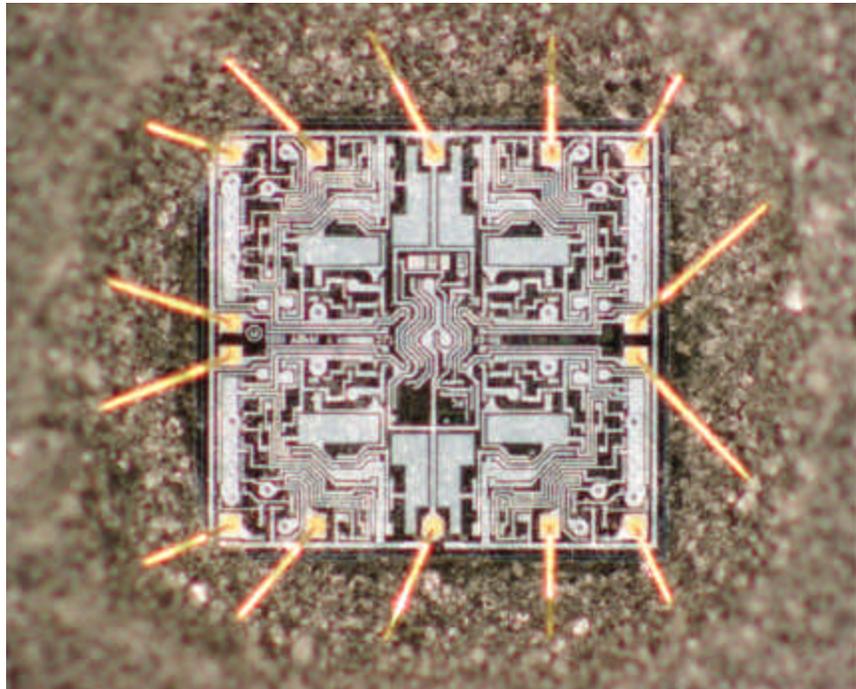


Figure 10. Internal view of SN 24 prepared for internal inspection. $\approx 20X$

Appended Photographs:

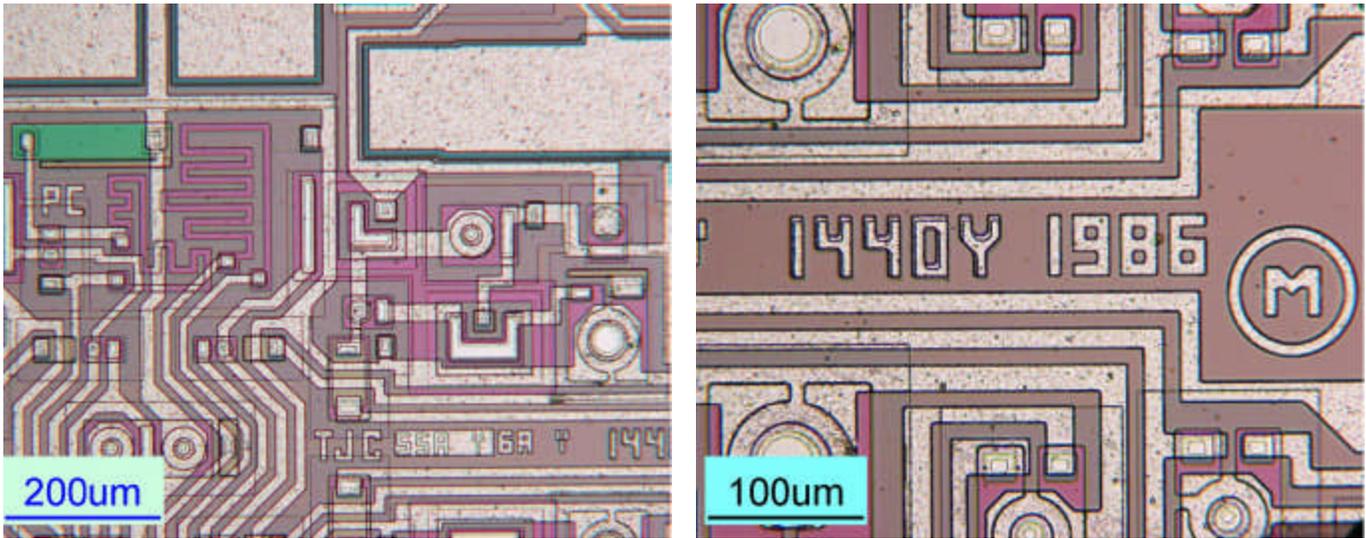


Figure 11. Optical micrograph images show general die features on SN 24.

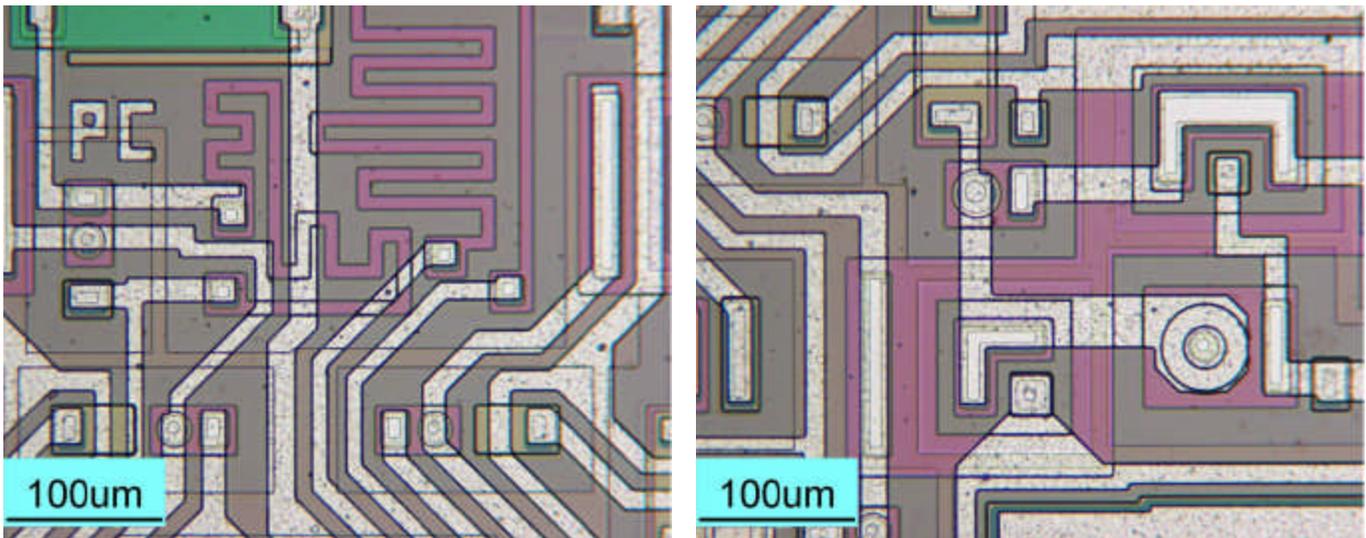


Figure 12. Optical micrograph images show general die features on SN 27.

Appended Photographs:

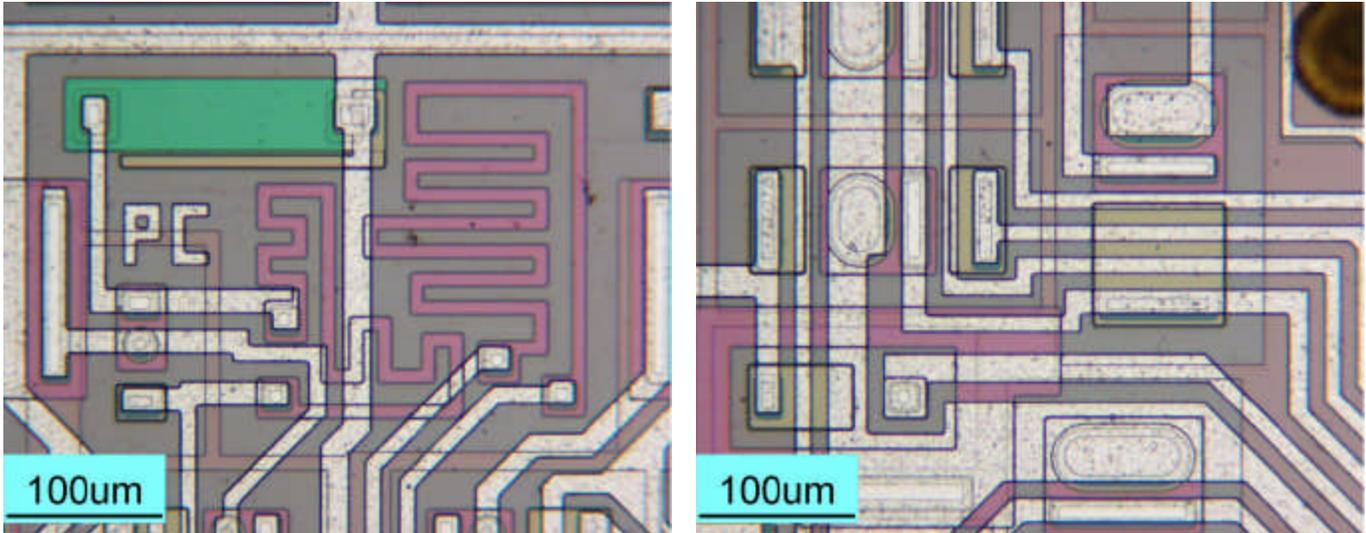


Figure 13. Optical micrograph images show general die features on SN 30.

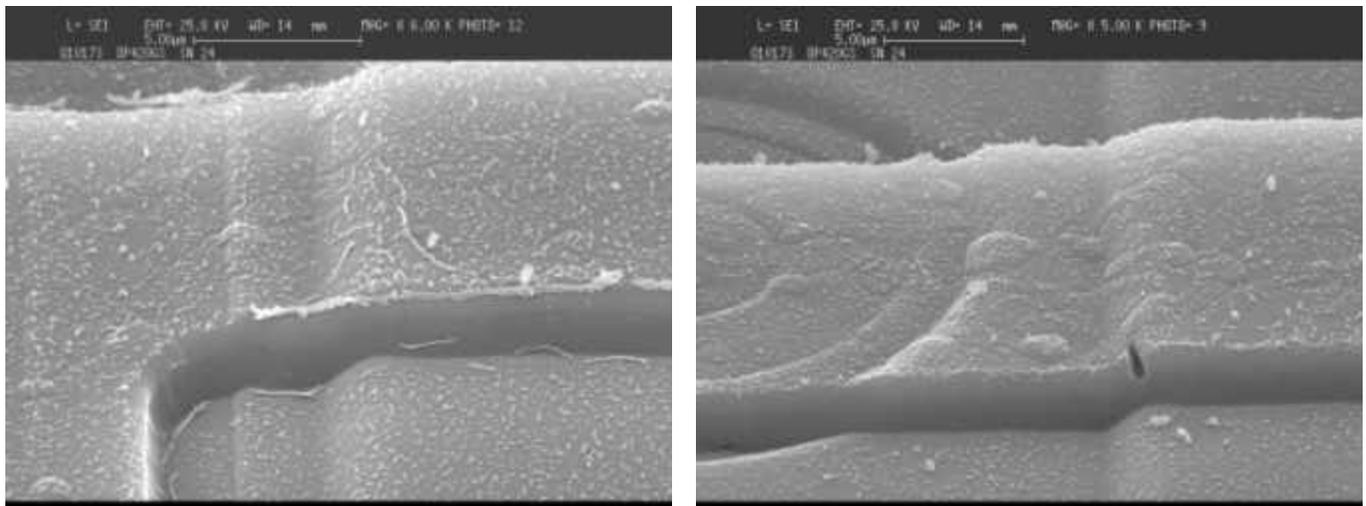


Figure 14. SEM micrographs of SN 24 show excellent step coverage.

Appended Photographs:

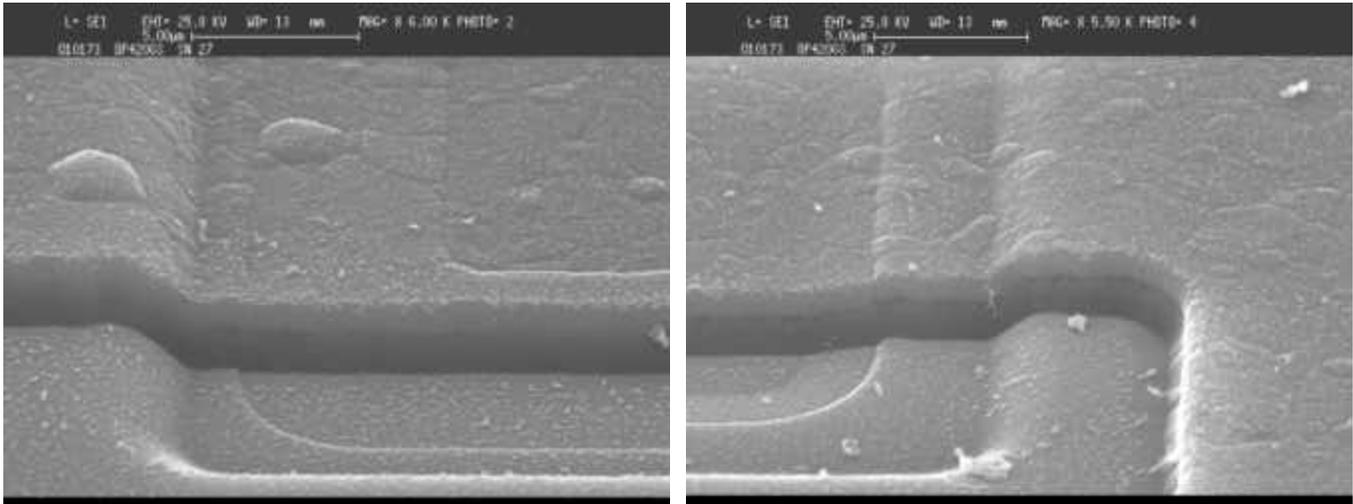


Figure 15. SEM micrographs of SN 27 show excellent step coverage.

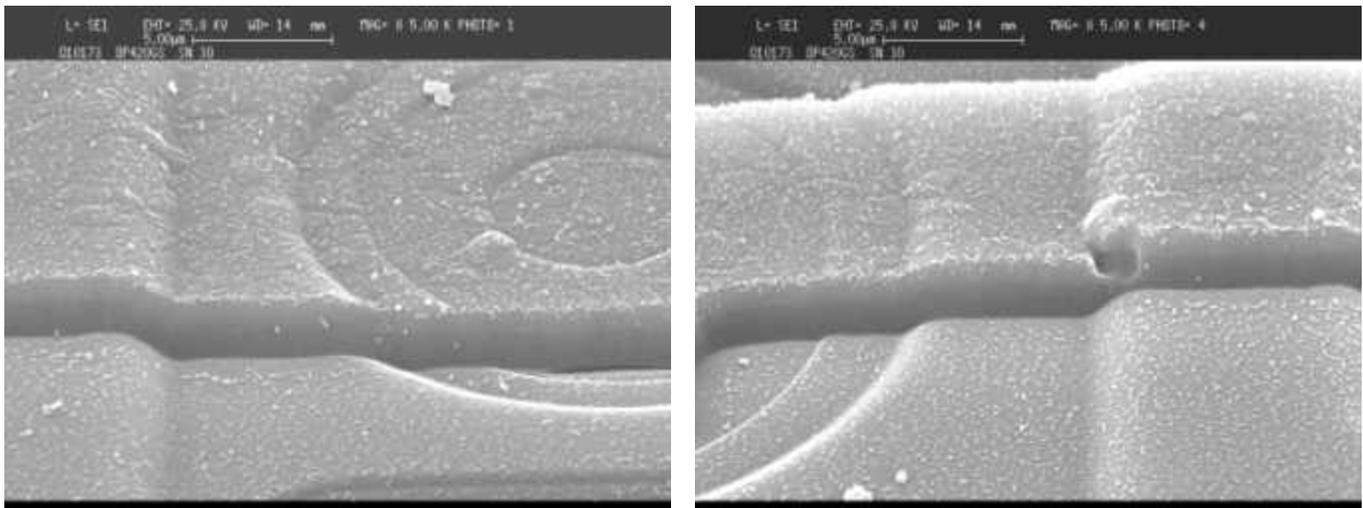


Figure 16. SEM micrographs of SN 30 show excellent step coverage. A minor 'mouse-bite' defect is visible in the right image.